DATA SHEET

74ALVT162827

20-bit buffer/line driver, non-inverting, with 30Ω termination resistors (3-State)

Product specification
Supersedes data of 1997 May 01
IC23 Data Handbook

1998 Feb 13

Philips
Semiconductors

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2.5V/3.3V 20-bit buffer/line driver, non-inverting, with 30Ω termination resistors (3-State)

74ALVT162827

FEATURES

- Multiple V_{CC} and GND pins minimize switching noise
- 5V I/O Compatible
- Live insertion/extraction permitted
- 3-State output buffers
- Outputs include series resistance of 30Ω making external termination resistors unnecessary
- Power-up 3-State
- Output capability: +12mA/–12mA
- Latch-up protection exceeds 500mA per Jedec Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model
- Bus hold data inputs eliminate the need for external pull-up resistors to hold unused inputs

DESCRIPTION

The 74ALVT162827 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive. It is designed for V_{CC} operation at 2.5V or 3.3V with I/O compatibility to 5V.

The 74ALVT162827 20-bit buffers provide high performance bus interface buffering for wide data/address paths or buses carrying parity. They have NOR Output Enables (n$\overline{OE}$1, n$\overline{OE}$2) for maximum control flexibility.

The 74ALVT162827 is designed with 30Ω series resistance in both the pull-up and pull-down output structures. This design reduces line noise in applications such as memory address drivers, clock drivers and bus receivers/transmitters.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T_{amb} = 25°C	TYPICAL		UNIT
			2.5V	3.3V	
t_{PLH} t_{PHL}	Propagation delay nAx to nBx or nBx to nAx	C_L = 50pF	2.7 2.3	2.2 2.0	ns
C_{IN}	Input capacitance DIR, $\overline{OE}$	V_I = 0V or V_{CC}	3	3	pF
C_{Out}	Output capacitance	$V_{I/O}$ = 0V or V_{CC}	9	9	pF
I_{CCZ}	Total supply current	Outputs disabled	40	70	µA

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
56-Pin Plastic SSOP Type III	–40°C to +85°C	74ALVT162827 DL	AV162827 DL	SOT371-1
56-Pin Plastic TSSOP Type II	–40°C to +85°C	74ALVT162827 DGG	AV162827 DGG	SOT364-1

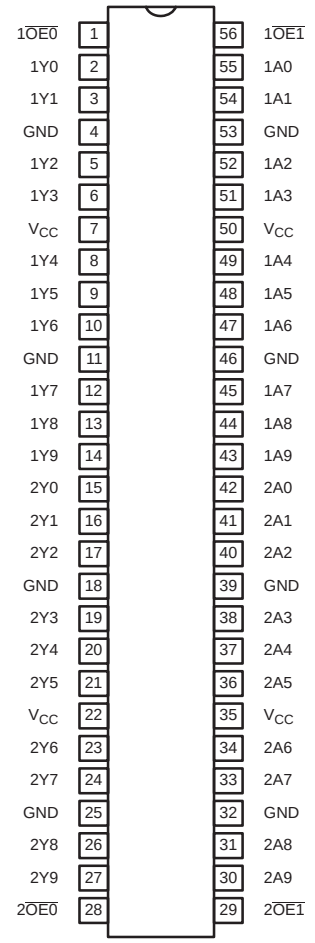
PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
55, 54, 52, 51, 49, 48, 47, 45, 44, 43, 42, 41, 40, 38, 37, 36, 34, 33, 31, 30	1A0 - 1A9 2A0 - 2A9	Data inputs
2, 3, 5, 6, 8, 9, 10, 12, 13, 14, 15, 16, 17, 19, 20, 21, 23, 24, 26, 27	1Y0 - 1Y9 2Y0 - 2Y9	Data outputs
1, 56, 28, 29	1$\overline{OE}$0, 1$\overline{OE}$1 2$\overline{OE}$0, 2$\overline{OE}$1	Output enable inputs (active-Low)
4, 11, 18, 25, 32, 39, 46, 53	GND	Ground (0V)
7, 22, 35, 50	V_{CC}	Positive supply voltage

2.5V/3.3V 20-bit buffer/line driver, non-inverting, with 30Ω termination resistors (3-State)

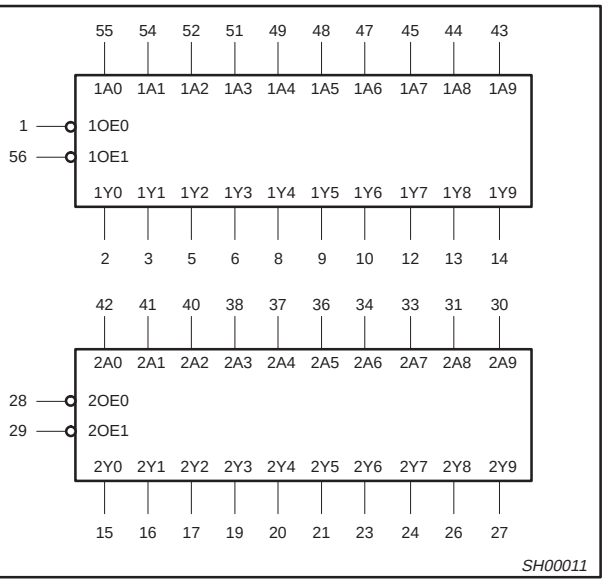
74ALVT162827

PIN CONFIGURATION



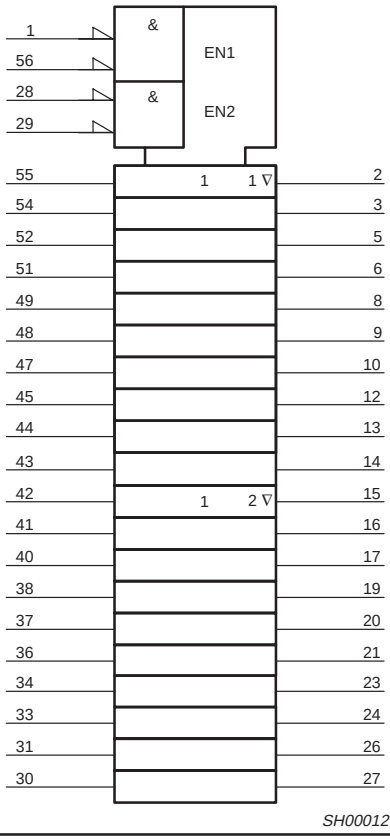
SH00010

LOGIC SYMBOL



SH00011

LOGIC SYMBOL (IEEE/IEC)



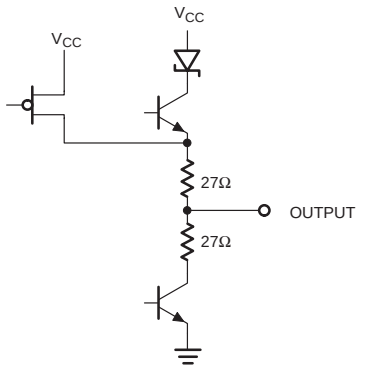
SH00012

FUNCTION TABLE

INPUTS		OUTPUTS	OPERATING MODE
$n\overline{OE}x$	nAx	nYx	
L	L	L	Transparent
L	H	H	Transparent
H	X	Z	High impedance

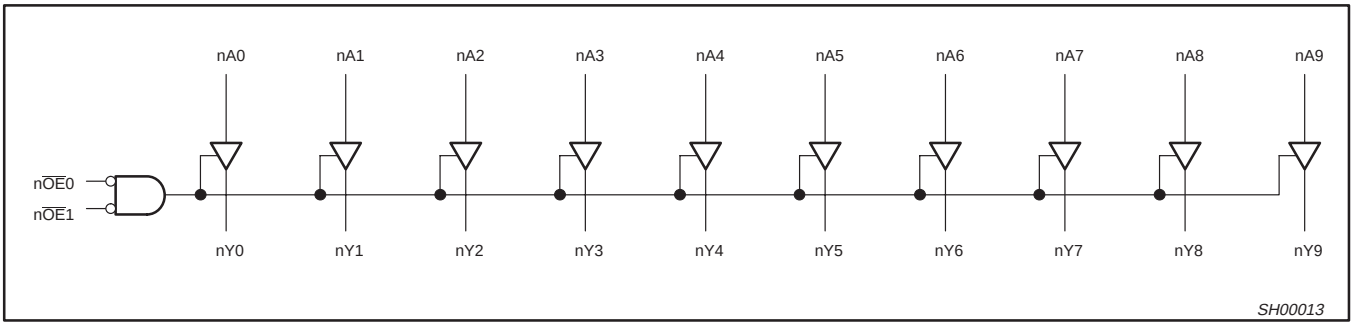
X = Don't care
Z = High impedance "off" state
H = High voltage level
L = Low voltage level

SCHEMATIC OF EACH OUTPUT



SW00206

LOGIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS[1, 2]

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		-0.5 to +7.0	V
I_{IK}	DC input diode current	$V_I < 0$	-18	mA
V_I	DC input voltage[3]		-1.2 to +7.0	V
I_{OK}	DC output diode current	$V_O < 0$	-50	mA
V_{OUT}	DC output voltage[3]	output in Off or High state	-0.5 to +5.5	V
I_{OUT}	DC output current	output in Low state	128	mA
T_{stg}	Storage temperature range		-65 to 150	°C

NOTES:
1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	2.5V RANGE LIMITS		3.3V RANGE LIMITS		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	DC supply voltage	2.3	2.7	3.0	3.6	V
V_I	Input voltage	0	5.5	0	5.5	V
V_{IH}	High-level input voltage	1.7		2.0		V
V_{IL}	Input voltage		0.7		0.8	V
I_{OH}	High-level output current		–8		–12	mA
I_{OL}	Low-level output current		12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate; Outputs enabled		10		10	ns/V
T_{amb}	Operating free-air temperature range	–40	+85	–40	+85	°C

DC ELECTRICAL CHARACTERISTICS (3.3V ±0.3V RANGE)

SYMBOL	PARAMETER	TEST CONDITIONS		LIMITS			UNIT
				Temp = -40°C to +85°C			
				MIN	TYP[1]	MAX	
V_{IK}	Input clamp voltage	V_{CC} = 3.0V; I_{IK} = –18mA			–0.85	–1.2	V
V_{OH}	High-level output voltage	V_{CC} = 3.0V; I_{OH} = –12mA		2.0	2.3		V
V_{OL}	Low–level output voltage	V_{CC} = 3.0V; I_{OL} = 12mA			0.5	0.8	V
I_I	Input leakage current	V_{CC} = 3.6V; V_I = V_{CC} or GND	Control pins		0.1	±1	µA
		V_{CC} = 0 or 3.6V; V_I = 5.5V			0.1	10	
		V_{CC} = 3.6V; V_I = V_{CC}	Data pins[4]		0.5	1	
		V_{CC} = 3.6V; V_I = 0			0.1	-5	
I_{OFF}	Off current	V_{CC} = 0V; V_I or V_O = 0 to 4.5V			0.1	±100	µA
I_{HOLD}	Bus Hold current Data inputs[6]	V_{CC} = 3V; V_I = 0.8V		75	130		µA
		V_{CC} = 3V; V_I = 2.0V		–75	–140		µA
		V_{CC} = 0V to 3.6V; V_{CC} = 3.6V		±500			µA
I_{EX}	Current into an output in the High state when $V_O > V_{CC}$	V_O = 5.5V; V_{CC} = 3.0V			10	125	µA
$I_{PU/PD}$	Power up/down 3-State output current[3]	$V_{CC} \leq$ 1.2V; V_O = 0.5V to V_{CC}; V_I = GND or V_{CC} OE/$\overline{OE}$ = Don't care			1	±100	µA
I_{OZH}	3-State output High current	V_{CC} = 3.6V; V_O = 3.0V; V_I = V_{IL} or V_{IH}			0.5	5	µA
I_{OZL}	3-State output Low current	V_{CC} = 3.6V; V_O = 0.5V; V_I = V_{IL} or V_{IH}			0.5	–5	µA
I_{CCH}	Quiescent supply current	V_{CC} = 3.6V; Outputs High, V_I = GND or V_{CC}, I_O = 0			0.07	0.1	mA
I_{CCL}		V_{CC} = 3.6V; Outputs Low, V_I = GND or V_{CC}, I_O = 0			3.9	5.5	
I_{CCZ}		V_{CC} = 3.6V; Outputs Disabled; V_I = GND or V_{CC}, I_O = 0[5]			0.07	0.1	
ΔI_{CC}	Additional supply current per input pin[2]	V_{CC} = 3V to 3.6V; One input at V_{CC}–0.6V, Other inputs at V_{CC} or GND			0.04	0.4	mA

NOTES:
1. All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.
2. This is the increase in supply current for each input at the specified voltage level other than V_{CC} or GND
3. This parameter is valid for any V_{CC} between 0V and 1.2V with a transition time of up to 10msec. From V_{CC} = 1.2V to V_{CC} = 3.3V ± 0.3V a transition time of 100µsec is permitted. This parameter is valid for T_{amb} = 25°C only.
4. Unused pins at V_{CC} or GND.
5. I_{CCZ} is measured with outputs pulled up to V_{CC} or pulled down to ground.
6. This is the bus hold overdrive current required to force the input to the opposite logic state.

AC CHARACTERISTICS (3.3V ±0.3V RANGE)

GND = 0V, t_R = t_F = 2.5ns, C_L = 50pF, R_L = 500Ω

SYMBOL	PARAMETER	WAVEFORM	LIMITS			UNIT
			T_{amb} = -40 to +85°C V_{CC} = +3.3V ±0.3V			
			MIN	TYP	MAX	
t_{PLH} t_{PHL}	Propagation delay nAx to nYx	1	1.0 1.0	2.2 2.0	3.3 3.0	ns
t_{PZH} t_{PZL}	Output enable time to High and Low level	2	1.5 1.0	3.4 2.4	5.6 3.7	ns
t_{PHZ} t_{PLZ}	Output disable time from High and Low level	2	1.5 1.0	3.4 2.7	5.2 4.5	ns

DC ELECTRICAL CHARACTERISTICS (2.5V ±0.2V RANGE)

SYMBOL	PARAMETER	TEST CONDITIONS		LIMITS			UNIT
				Temp = -40°C to +85°C			
				MIN	TYP[1]	MAX	
V_{IK}	Input clamp voltage	V_{CC} = 2.3V; I_{IK} = –18mA			–0.85	–1.2	V
V_{OH}	High-level output voltage	V_{CC} = 2.3V; I_{OH} = –8mA		1.7	2.3		V
V_{OL}	Low-level output voltage	V_{CC} = 2.3V; I_{OL} = 12mA			0.5	0.7	V
I_I	Input leakage current	V_{CC} = 2.7V; V_I = V_{CC} or GND	Control pins		0.1	±1	µA
		V_{CC} = 0 or 2.7V; V_I = 5.5V			0.1	10	
		V_{CC} = 2.7V; V_I = V_{CC}	Data pins[4]		0.1	1	
		V_{CC} = 2.7V; V_I = 0			0.1	-5	
I_{OFF}	Off current	V_{CC} = 0V; V_I or V_O = 0 to 4.5V			0.1	±100	µA
I_{HOLD}	Bus Hold current Data inputs[6]	V_{CC} = 2.3V; V_I = 0.7V			115		µA
		V_{CC} = 2.3V; V_I = 1.7V			–10		
I_{EX}	Current into an output in the High state when $V_O > V_{CC}$	V_O = 5.5V; V_{CC} = 2.3V			10	125	µA
$I_{PU/PD}$	Power up/down 3-State output current[3]	$V_{CC} \leq$ 1.2V; V_O = 0.5V to V_{CC}; V_I = GND or V_{CC}; $\overline{OE}$/OE = Don't care			1	100	µA
I_{OZH}	3-State output High current	V_{CC} = 2.7V; V_O = 2.3V; V_I = V_{IL} or V_{IH}			0.5	5	µA
I_{OZL}	3-State output Low current	V_{CC} = 2.7V; V_O = 0.5V; V_I = V_{IL} or V_{IH}			0.5	–5	µA
I_{CCH}	Quiescent supply current	V_{CC} = 2.7V; Outputs High, V_I = GND or V_{CC}, I_O = 0			0.04	0.1	mA
I_{CCL}		V_{CC} = 2.7V; Outputs Low, V_I = GND or V_{CC}, I_O = 0			3.5	5.0	
I_{CCZ}		V_{CC} = 2.7V; Outputs Disabled; V_I = GND or V_{CC}, I_O = 0[5]			0.04	0.1	
ΔI_{CC}	Additional supply current per input pin[2]	V_{CC} = 2.3V to 2.7V; One input at V_{CC}–0.6V, Other inputs at V_{CC} or GND			0.04	0.4	mA

NOTES:
1. All typical values are at V_{CC} = 2.5V and T_{amb} = 25°C.
2. This is the increase in supply current for each input at the specified voltage level other than V_{CC} or GND
3. This parameter is valid for any V_{CC} between 0V and 1.2V with a transition time of up to 10msec. From V_{CC} = 1.2V to V_{CC} = 2.5V ± 0.2V a transition time of 100µsec is permitted. This parameter is valid for T_{amb} = 25°C only.
4. Unused pins at V_{CC} or GND.
5. I_{CCZ} is measured with outputs pulled up to V_{CC} or pulled down to ground.
6. Not guaranteed.

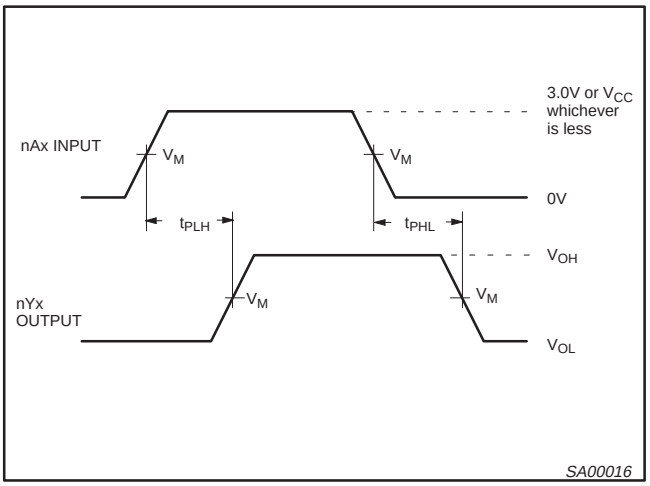
AC CHARACTERISTICS (2.5V ±0.2V RANGE)

GND = 0V, t_R = t_F = 2.5ns, C_L = 50pF, R_L = 500Ω

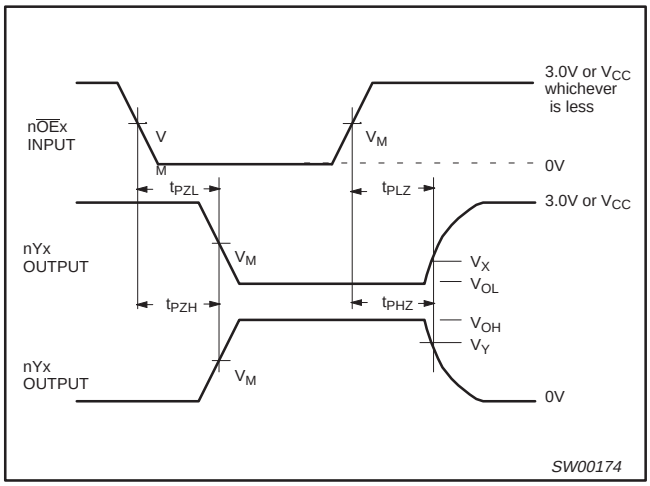
SYMBOL	PARAMETER	WAVEFORM	LIMITS			UNIT
			T_{amb} = -40 to +85°C V_{CC} = +2.5V ±0.2V			
			MIN	TYP	MAX	
t_{PLH} t_{PHL}	Propagation delay nAx to nYx	1	1.5 1.5	2.7 2.3	4.5 3.5	ns
t_{PZH} t_{PZL}	Output enable time to High and Low level	2	2.5 1.5	4.7 2.9	7.5 4.7	ns
t_{PHZ} t_{PLZ}	Output disable time from High and Low level	2	1.5 1.0	3.2 2.4	5.2 4.0	ns

AC WAVEFORMS

V_M = 1.5V for $V_{CC} \geq$ 3.0V; $V_M = V_{CC}/2$ for $V_{CC} \leq$ 2.7V
$V_X = V_{OL}$ + 0.3V for $V_{CC} \geq$ 3.0V; $V_X = V_{OL}$ + 0.15V for $V_{CC} \leq$ 2.7V
$V_Y = V_{OH}$ – 0.3V for $V_{CC} \geq$ 3.0V; $V_Y = V_{OH}$ – 0.15V for $V_{CC} \leq$ 2.7V

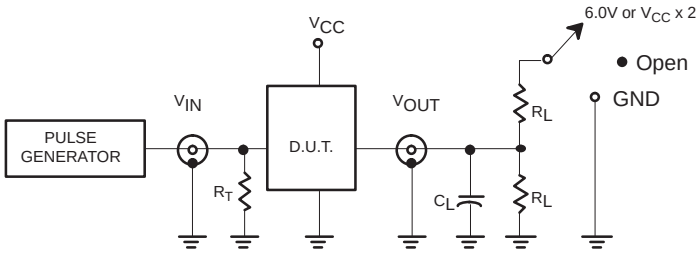


Waveform 1. Input (nAx) to Output (nYx) Propagation Delays

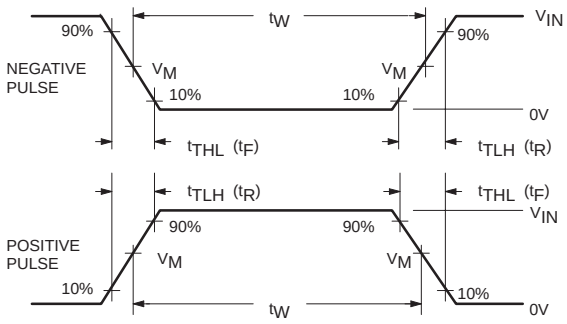


Waveform 2. 3-State Output Enable and Disable Times

TEST CIRCUIT AND WAVEFORM



Test Circuit for 3-State Outputs



V_M = 1.5V or $V_{CC}/2$ whichever is less
Input Pulse Definition

SWITCH POSITION

TEST	SWITCH
t_{PLZ}/t_{PZL}	6V or $V_{CC\ x\ 2}$
t_{PLH}/t_{PHL}	Open
t_{PHZ}/t_{PZH}	GND

DEFINITIONS

R_L = Load resistor; see AC CHARACTERISTICS for value.

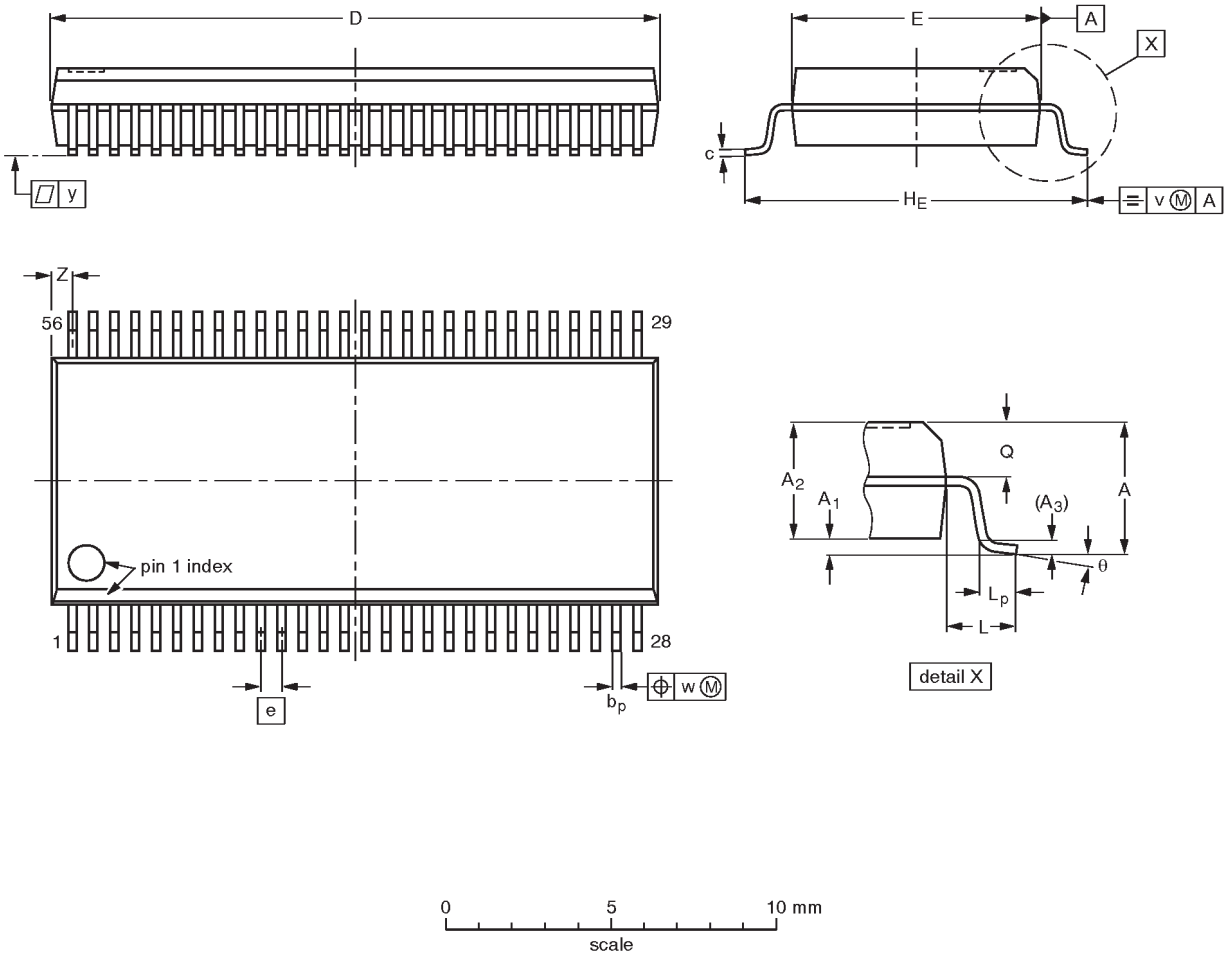
C_L = Load capacitance includes jig and probe capacitance: See AC CHARACTERISTICS for value.

R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

FAMILY	INPUT PULSE REQUIREMENTS				
	Amplitude	Rep. Rate	t_W	t_R	t_F
74ALVT16	3.0V or V_{CC} whichever is less	≤ 10MHz	500ns	≤ 2.5ns	≤ 2.5ns

SW00025

SSOP56: plastic shrink small outline package; 56 leads; body width 7.5 mm **SOT371-1**



DIMENSIONS (mm are the original dimensions)

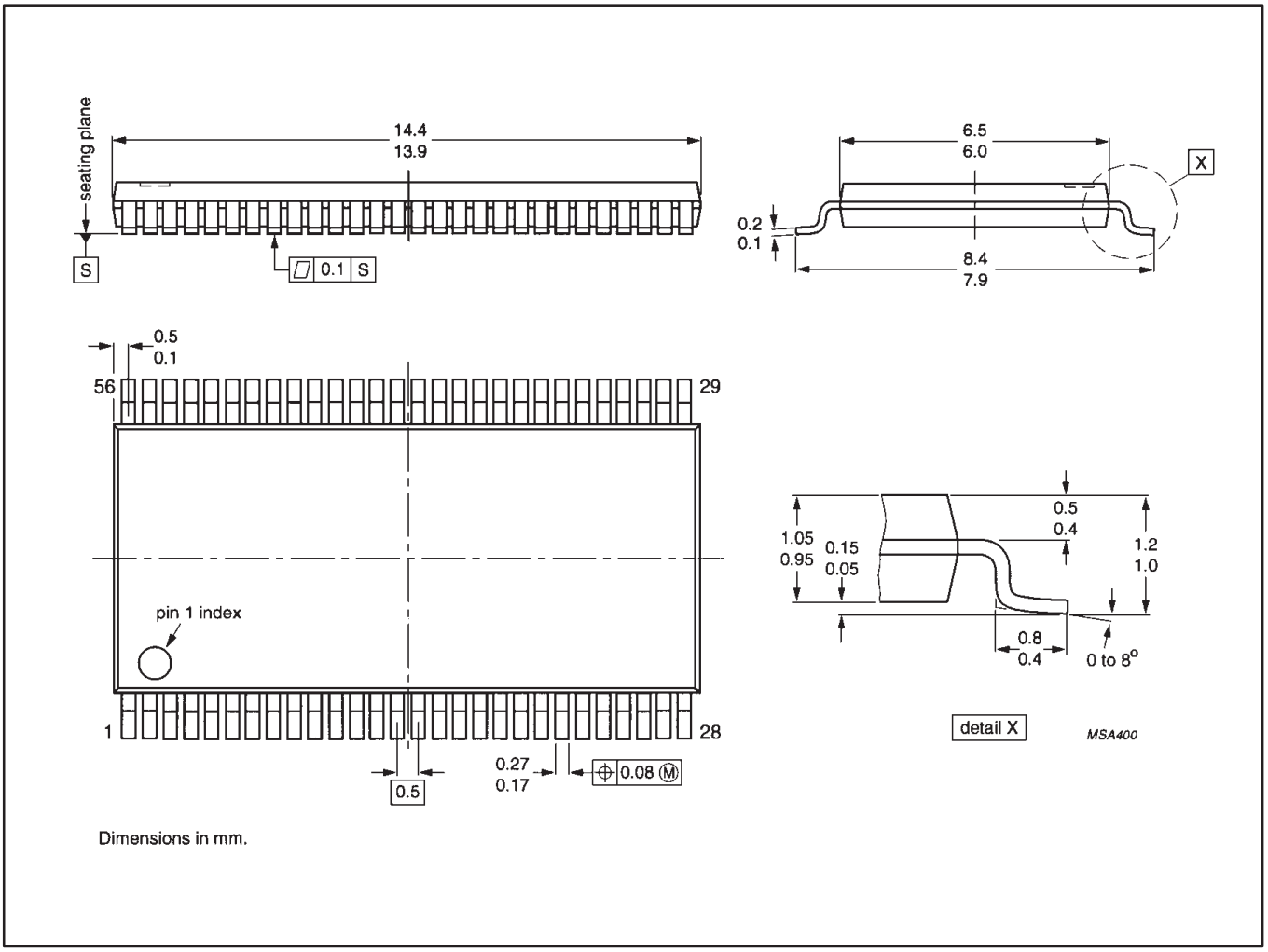
UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	18.55 18.30	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT371-1		MO-118AB				~~93-11-02~~ 95-02-04

TSSOP56: plastic thin shrink small outline package; 56 leads; body width 6.1mm **SOT364-1**



Dimensions in mm.

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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